

Low Contact Wafer Transfers

High Performance Wafer Handling Products

LCTAS8 (200mm) and LCTAS6 (150mm)

Standard, thin, or fragile substrate (GaAs) mass wafer transfer system. ↓

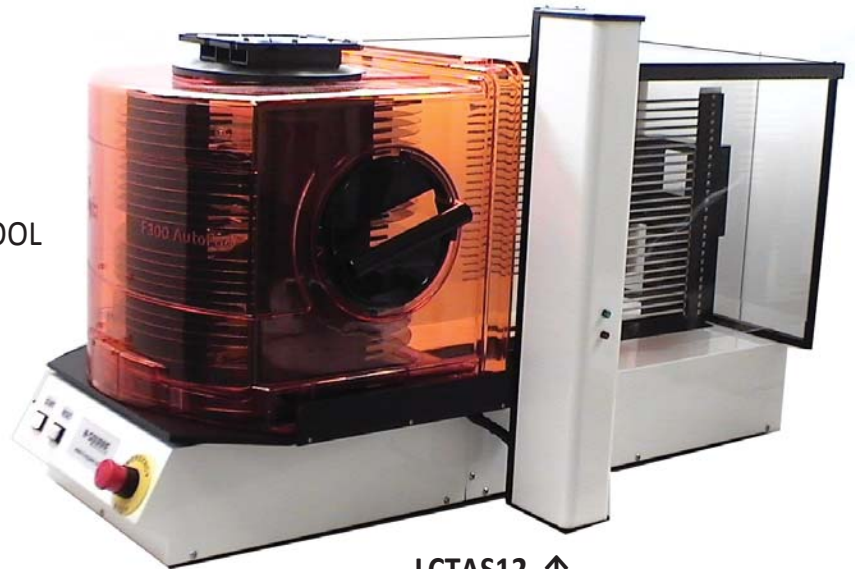
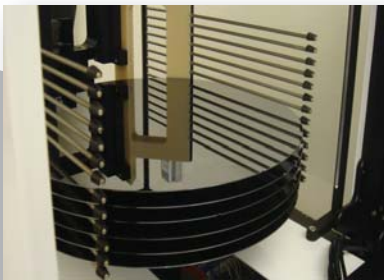


Low Contact Transfer Systems

H-Square's small footprint, high performance, horizontal low contact wafer transfer systems safely mass transfer all wafers from an existing carrier into another carrier. Wafers are gently lifted from a shipping or process carrier, brought into the protective housing, and then can be replaced in any similar-pitch carrier. Optical and mechanical wafer sensing and mapping (300mm product only), combine with software logic to guard against operator errors. All LCT systems are Class One cleanroom approved, user-friendly, reliable, fast, and safe.

Custom Product LCT Systems

H-Square has developed several LCT custom product designs. Including 200mm to 300mm FOUF insert "bridge-tool" transfers, 300mm SEMITOOL Clamshell transfers, Bi-pitch cassette LCT transfers, and ultra thin wafer (<300 micron) transfers.



LCTAS12 ↑

300mm FOUF-to-FOSB, FOUF-to-FOUF, or FOUF-to-Metal Cassette Mass Transfer System.

Wafer Contact Material: Kynar® PVDF

Polyvinylidene Fluoride (PVDF) is a high purity material with good wear resistance and outstanding chemical resistance.

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